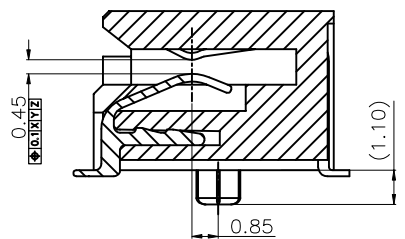
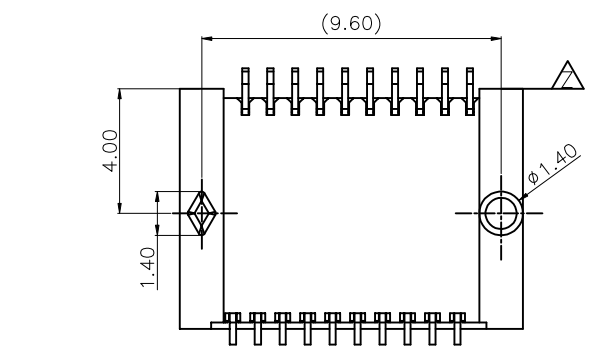
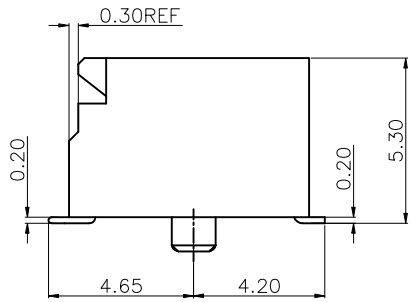
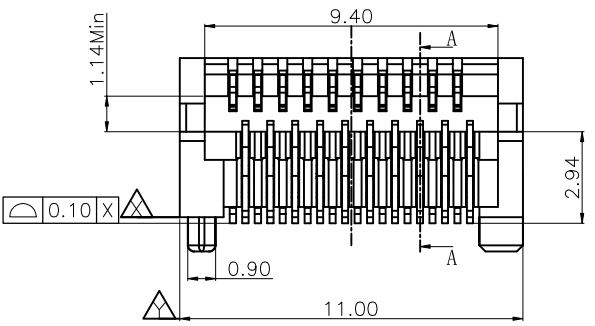
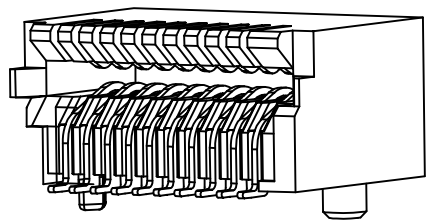
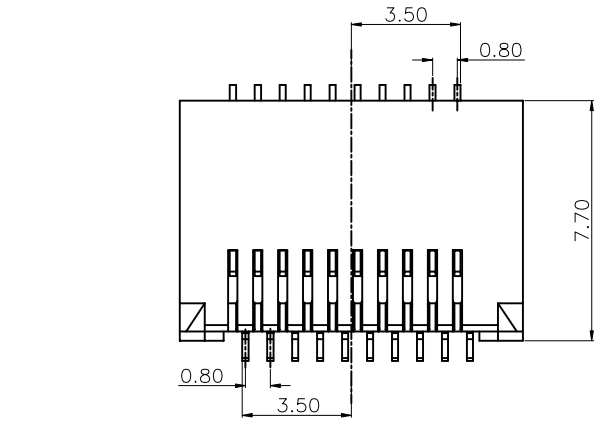
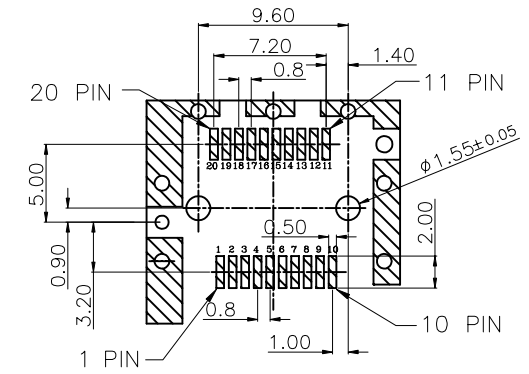


REVISION RECORD		
REV	DESCRIPTION	DRFT
10	A-release	Roy 11/12/2014



A-A SECTION

NOTE:  
MATERIAL:  
1. TERMINAL: COPPER ALLOY.  
2. HOUSING: LCP UL 94V-0\BLACK.  
PLATING:  
1. 1.27um MIN. Ni UNDERPLATING.  
2. 0.76um MIN. MATTE TIN PLATING ON SMT AREA.  
3. 0.76um MIN. GOLD PLATING ON CONTACT AREA.  
MECHANICAL:  
1. DURABILITY: 100 CYCLES MIN.  
2. INSERTION AND EXTRACTION FORCE: 40N MAX & 11.5N MAX.  
ENVIRONMENTAL:  
1. CONTACT RESISTANCE: 20 MILLIOHMS MAX INITIAL.  
2. DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/MIN.  
3. OPERATION: -40°C~+85°C.  
4. STORAGE: -55°C~+105°C.  
5. REFLOW SOLDERING TEMPERATURE: 255°C~265°C(5~10 SECONDS).  
6. ROHS COMPLIANT.



PC BOARD LAYOUT  
COMPONENT SIDE SHOWN

DETACHED LISTS	MM (INCH)		DFTO Roy	DATE 10/08/2014	<b>Pulse Electronics</b>	<b>RoHS Compliant</b>
	TOLERANCES EXCEPT AS NOTED		CHKD Victor	DATE 10/08/2014		
	MM		APPVL Victor	DATE 10/08/2014	TITLE <b>SFP+ 1X1 CONNECTOR</b>	
	.0 ± 0.20	±	MATERIAL :			
	.00 ± 0.15	±	QTY :			
.000 ± 0.075	±	FINISH :		DRAWING NO. SFPCC-1001-L	SIZE A3	REV 10
ANGLES ± 0.5°		SCALE : 1:1		DO NOT SCALE DRAWING		SHEET 1 OF 1
THIRD ANGLE PROJECTION						